What is claimed is:

1. A method of producing a CMP pad comprising:

forming a stack comprising a board, a CMP pad material adjacent said board, and a backing having an first adhesive on at least a portion of a side adjacent said CMP pad material and a second adhesive including a pressure sensitive adhesive (PSA) and a release liner on at least a portion of a side opposite said CMP pad material, where the material of said board and said CMP pad material have similar composition; and

compressing said stack to adhere said backing to said CMP pad material and form a laminate having a top side including said CMP pad material and a bottom side including said PSA and release liner; and

separating said board from said laminate.

2. The method of claim 1, wherein said compressing includes feeding said stack through pinch rollers.

3. The method of claim 2, wherein said pinch rollers have a clearance of approximately 70% to approximately 95% of the thickness of said stack.

4. The method of claim 1, wherein the material of said board and said CMP pad material are thermoplastics.

5. The method of claim 4, wherein the material of said board and said CMP pad material are elastomers.

6. The method of claim 5, wherein said elastomer is cast urethane.

7. The method of claim 5, wherein said elastomer is foam urethane.

8. The method of claim 1, wherein the planar dimensions of said board are equal to or greater than the planar dimensions of said CMP pad material.

9. The method of claim 5, wherein the planar dimensions of said board is at least 10% larger than the planar dimensions of said CMP pad material.

10. The method of claim 1, wherein said board has a thickness of from about 1/16" to about 1/4" with a thickness tolerance of less than about 3/100".

11. The method of claim 1, wherein said board has a recess on one face thereof, where said recess has a planar shape equal to larger than the planar shape of said CMP pad material and a depth approximately 50% to approximately 90% of the thickness of said CMP pad material.

12. The method of claim 1, wherein said first adhesive is a thermoset adhesive, and wherein

said conditions include heating said backing to a temperature sufficient to activate said first adhesive.

13. The method of claim 12, wherein said compressing includes feeding said stack through pinch rollers, wherein one of said pinch rollers compresses said first backing side and is heated.

14. The method of claim 1, wherein said first adhesive is a PSA.

15. The method of claim 14, wherein said backing includes a CMP sub-pad between said first adhesive and said second adhesive.

16. The method of claim 14, wherein said board is a first board, wherein said stack further comprises a second board adjacent said release liner, and further comprising separating said second board from said laminate.

17. A method of producing a CMP pad comprising:

forming a stack comprising a first board, a CMP pad material adjacent said board, a backing having an first adhesive including a pressure sensitive adhesive (PSA) on at least a portion of a side adjacent said CMP pad material and a second adhesive including a pressure sensitive adhesive (PSA) and a release liner on at least a portion of a side opposite said CMP pad material, and a second board adjacent said release liner, where the material of said first board, the material of said second board and said CMP pad material have similar composition; and

compressing said stack to adhere said backing to said CMP pad material and form a laminate having a top side including said CMP pad material and a bottom side including said PSA and release liner; and

separating said first board and said second board from said laminate.

18. The method of claim 17, wherein said compressing includes feeding said stack through pinch rollers.

19. The method of claim 17, wherein said pinch rollers have a clearance of approximately 70% to approximately 95% of the thickness of said stack.

20. The method of claim 17, wherein the material of said board, the material of said second board, and said CMP pad material are urethane.

21. The method of claim 20, wherein said urethane is cast urethane.

22. The method of claim 20, wherein said urethane is foam urethane.

23. The method of claim 17, wherein the planar dimensions of said first board and said second board are each equal to or greater than larger than the planar dimensions of said CMP pad

material.

24. The method of claim 17, wherein the planar dimensions of said first board and said second board are each at least 10% larger than the planar dimensions of said CMP pad material.

25. The method of claim 17, wherein said first board and said second board each have a thickness of from about 1/16" to about 1/4" with a thickness tolerance of less than about 3/100".

26. The method of claim 17, wherein said first board has a recess on one face thereof, where said recess has a planar shape equal to larger than the planar shape of said CMP pad material and a depth approximately 50% to approximately 90% of the thickness of said CMP pad material.

27. The method of claim 17, wherein said backing includes a CMP sub-pad between said first adhesive and said second adhesive.

28. The method of claim 17, wherein said board is a first board, wherein said stack further comprises a second board adjacent said release liner, and further comprising separating said second board from said laminate.

29. A device to support the lamination of a CMP pad comprising a CMP pad material having planar dimensions comprising:

a board having a similar composition to the CMP pad material and having planar dimensions equal to or greater than the planar dimensions of said CMP pad material

30. The device of claim 29, wherein said board and said CMP pad material are urethane.

31. The device of claim 30, wherein said board and said CMP pad material are cast urethane.

31. The device of claim 31, wherein said board and said CMP pad material are foam urethane.

32. The device of claim 27, wherein the planar dimensions of said board is at least 10% larger than the planar dimensions of said CMP pad material.

33. The device of claim 27, wherein said board has a thickness of from about 1/16" to about 1/4" with a thickness tolerance of less than about 3/100".

34. The device of claim 27, wherein said board has a recess on one face thereof, where said recess has a planar shape equal to larger than the planar shape of said CMP pad material and a depth approximately 50% to approximately 90% of the thickness of said CMP pad material.